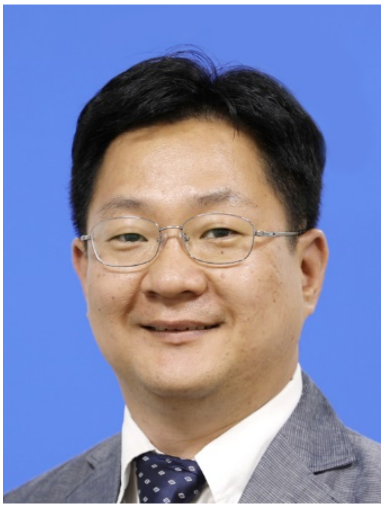
BIOGRAPHY

Advanced Packaging Summit 2025



Name: TaeKyeong Hwang
Title/ Position: Sr.Director / R&D Product Development Division Manager
Company: Amkor Technology

TaeKyeong Hwang, Ph.D. is currently R&D Product Development Division Manager who is in charge of advanced package development & transfer to mass production in Amkor Technology, Inc. His role covered advanced wafer level package, wafer level fan-out package (WLFO) and high density fan-out package (SWIFT®, S-SWIFT™, S-Connect) platforms and related process. He joined Amkor Technology, Inc. in 2005 as R&D engineer and has been working for package characterization engineering (simulation, 2nd level reliability tests), packaging material & process development manager and advanced SIP product development manager.

Hwang received Ph.D. in the field of solder joint reliability assessments with microstructure effects from Korea Advanced Institute of Science and Technology (KAIST).